

Super FAP-E^{3S} Low Qg Built-in FRED series

N-Channel enhancement mode power MOSFET

■ Features

Low on-state resistance
Low switching loss
easy to use
(more controllable switching dV/dt by R_g)
The reliability trial conforms to AEC Q101.
100% avalanche tested

■ Applications

Automotive switching applications

■ Absolute Maximum Ratings at $T_c=25^\circ\text{C}$ (unless otherwise specified)

Description	Symbol	Characteristics	Unit	Remarks
Drain-Source Voltage	V_{DS}	600	V	
	V_{DSX}	600	V	$V_{GS}=-30\text{V}$
Continuous Drain Current	I_D	± 22	A	
Pulsed Drain Current	I_{DP}	± 88	A	
Gate-Source Voltage	V_{GS}	± 30	V	
Non-Repetitive Maximum Avalanche current	I_{AS}	22	A	Note*1
Non-Repetitive Maximum Avalanche Energy	E_{AS}	470	mJ	Note*2
Peak Diode Recovery dV/dt	dV/dt	4.7	kV/ μs	Note*3
Peak Diode Recovery di/dt	$-di/dt$	100	A/ μs	Note*4
Maximum Power Dissipation	P_D	400	W	
Operating and Storage Temperature range	T_{ch}	150	$^\circ\text{C}$	
	T_{stg}	-55 to +150	$^\circ\text{C}$	

Note*1 : $T_{ch} \leq 150^\circ\text{C}$, See Fig.1 and Fig.2

Note*2 : Starting $T_{ch}=25^\circ\text{C}$, $L=1779\mu\text{H}$, $V_{CC}=60\text{V}$, $R_G=50\Omega$, See Fig.1 and Fig.2

E_{AS} limited by maximum channel temperature and avalanche current.

See to Avalanche Energy graph of page 5

Note*3 : $IF \leq -I_D$, $-di/dt=100\text{A}/\mu\text{s}$, $V_{CC} \leq BV_{DSS}$, $T_{ch} \leq 150^\circ\text{C}$

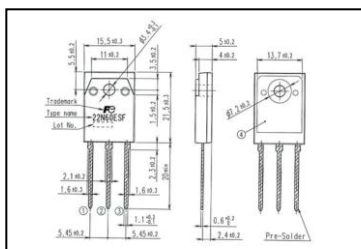
Note*4 : $IF \leq -I_D$, $dV/dt=4.7\text{kV}/\mu\text{s}$, $V_{CC} \leq BV_{DSS}$, $T_{ch} \leq 150^\circ\text{C}$

■ Electrical Characteristics at $T_c=25^\circ\text{C}$ (unless otherwise specified)

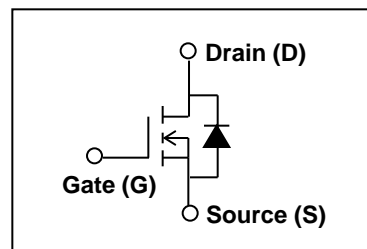
Static Ratings

Description	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D=1\text{mA}$ $V_{GS}=0\text{V}$	600	—	—	V
	BV_{DSX}	$I_D=1\text{mA}$ $V_{GS}=-30\text{V}$	600	—	—	V
Gate Threshold Voltage	$V_{GS(th)}$	$I_D=250\mu\text{A}$ $V_{DS}=V_{GS}$	3.2	4.2	5.2	V
Zero Gate Voltage Drain current	I_{DSS}	$V_{DS}=600\text{V}$ $V_{GS}=0\text{V}$ $T_a=25^\circ\text{C}$	—	2	10	μA
		$V_{DS}=480\text{V}$ $V_{GS}=0\text{V}$ $T_a=125^\circ\text{C}$	—	0.7	2	mA
Gate-Source Leakage current	I_{GSS}	$V_{GS}=30\text{V}$ $V_{DS}=0\text{V}$	—	10	100	nA
Drain-Source On-State Resistance	$R_{DS(on)}$	$I_D=11\text{A}$ $V_{GS}=10\text{V}$	—	250	290	m Ω

■ Outline Drawings [mm]



■ Equivalent circuit schematic



Dynamic Ratings

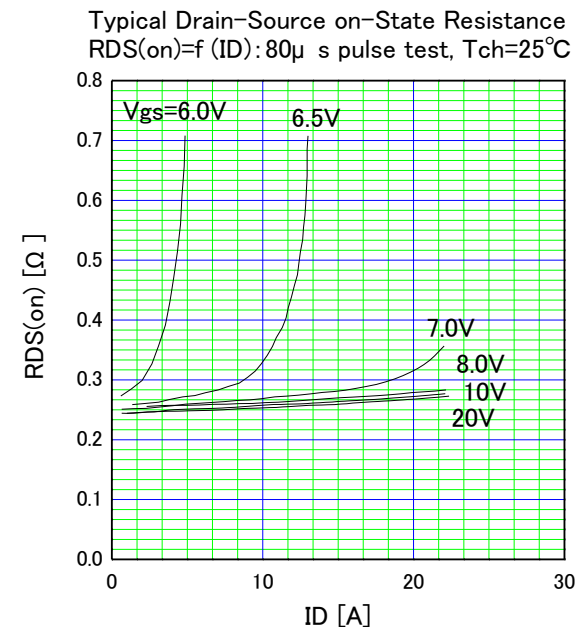
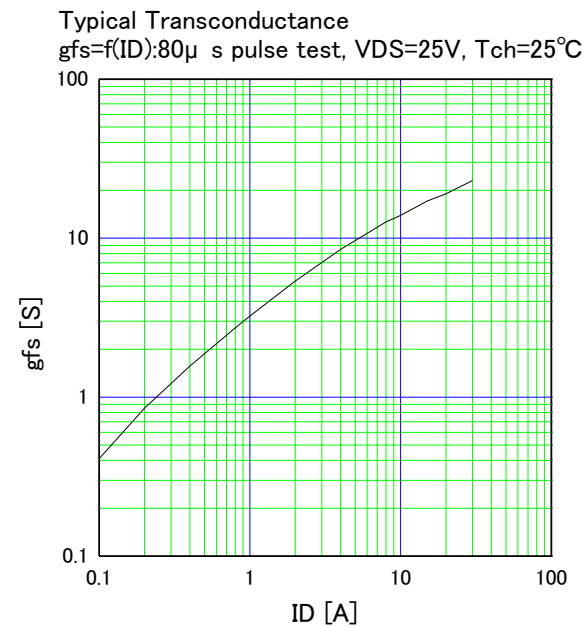
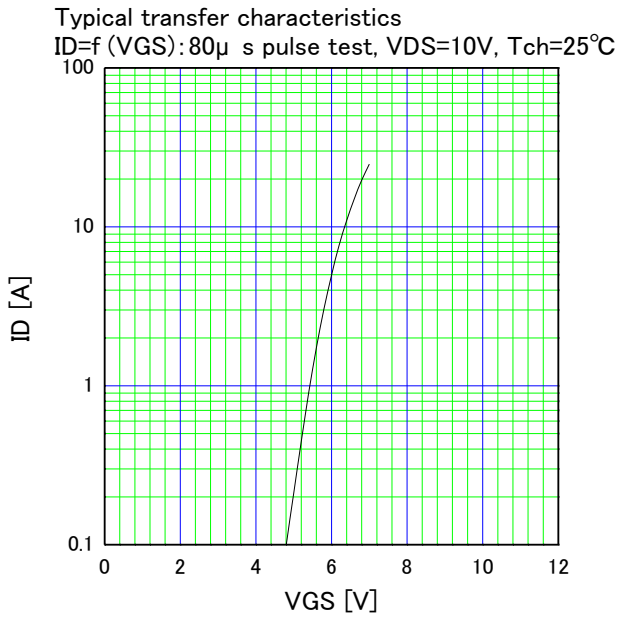
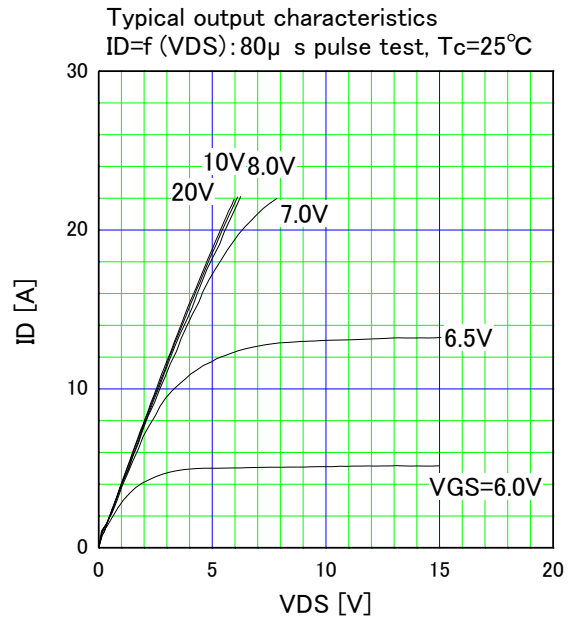
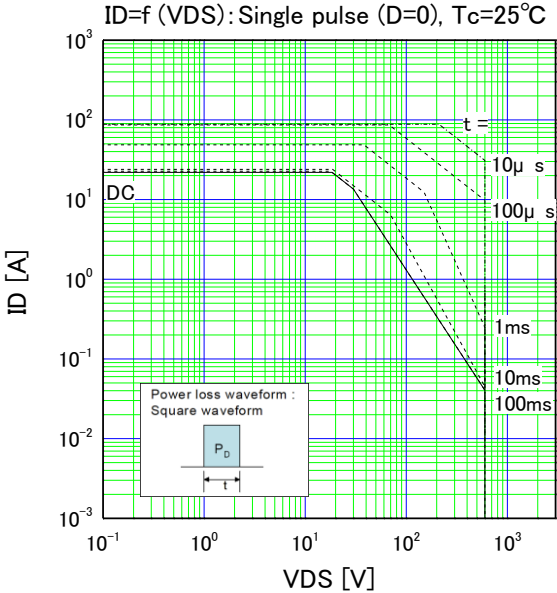
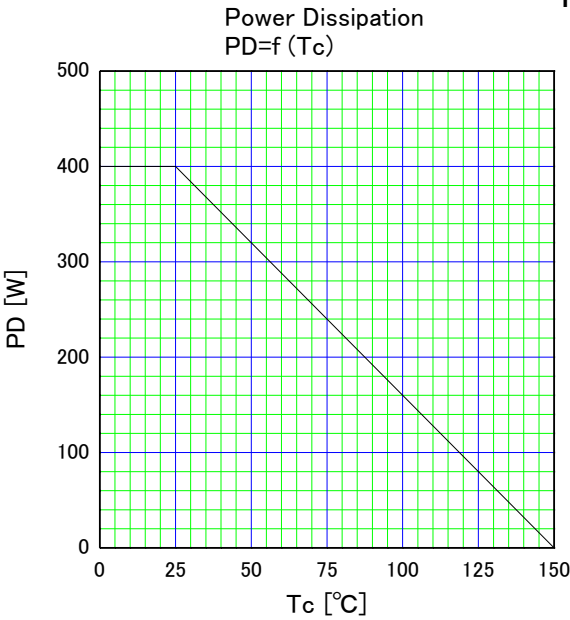
Description	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward Transconductance	g_{fs}	$I_D=11A$ $V_{DS}=25V$	8	—	—	S
Input Capacitance	C_{iss}	$V_{DS}=25V$ $V_{GS}=0V$ $f=1MHz$	—	3330	—	pF
Output Capacitance	C_{oss}		—	400	—	
Reverse Transfer Capacitance	C_{rss}		—	23	—	
Turn-On Time	$t_{d(on)}$	$V_{CC}=300V, V_{GS}=10V$ $I_D=11A, R_G=10\Omega$ See Fig.3 and Fig.4	—	50	—	ns
	t_r		—	80	—	
Turn-Off Time	$t_{d(off)}$		—	120	—	
	t_f		—	30	—	
Total Gate Charge	Q_G	$V_{DD}=300V, I_D=22A$ $V_{GS}=10V$ See Fig.5	—	95	—	nC
Gate-Source Charge	Q_{GS}		—	32	—	
Gate-Drain Charge	Q_{GD}		—	42	—	

Reverse Ratings

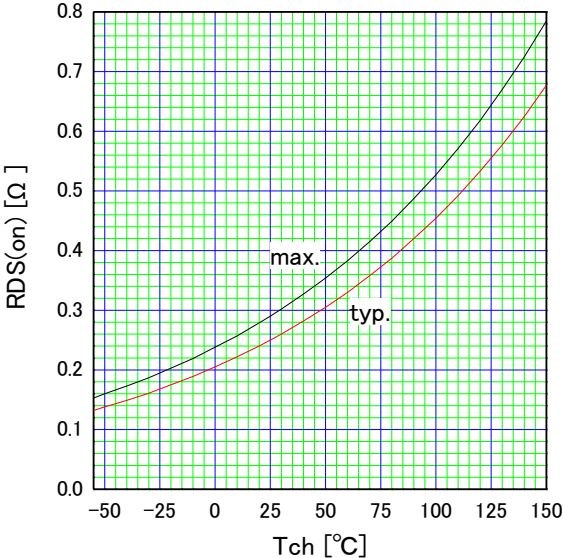
Description	Symbol	Conditions	Min.	Typ.	Max.	Unit
Avalanche Capability	I_{AV}	$L=1779\mu H, T_{ch}=25^\circ C$ See Fig.1 and Fig.2	22	—	—	A
Diode Forward On- Voltage	V_{SD}	$I_F=22A, V_{GS}=0V$ $T_{ch}=25^\circ C$	—	1.10	1.5	V
Reverse Recovery Time	t_{rr}	$I_F=22A, V_{GS}=0V$ $-di/dt=100A/\mu s$ $T_{ch}=25^\circ C$	—	150	—	ns
Reverse Recovery Charge	Q_{rr}		—	0.6	—	μC

■ Thermal Characteristics

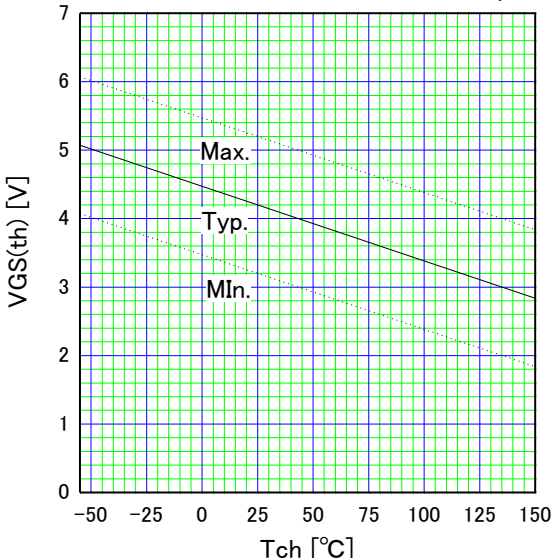
Description	Symbol	Min.	Typ.	Max.	Unit
Cannel to Case	$R_{th(ch-c)}$	—	—	0.312	$^\circ C/W$
Cannel to Ambient	$R_{th(ch-a)}$	—	—	50.0	$^\circ C/W$



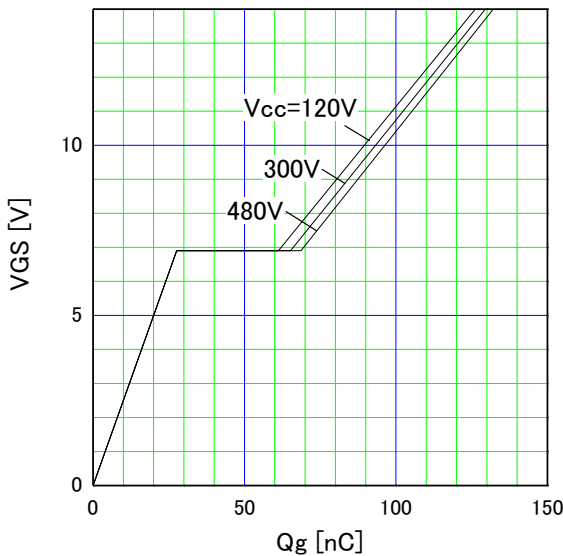
Drain-source on-state resistance
 $R_{DS(on)}=f(T_{ch}): I_D=11A, V_{GS}=10V$



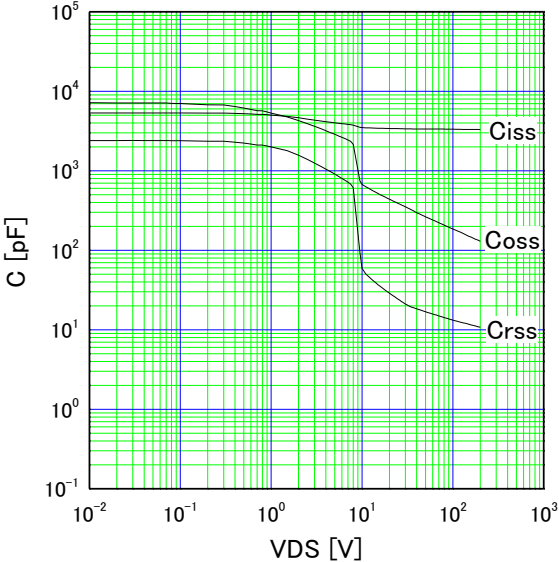
Gate Threshold Voltage vs. T_{ch}
 $V_{GS(th)}=f(T_{ch}): V_{DS}=V_{GS}, I_D=250\mu A$



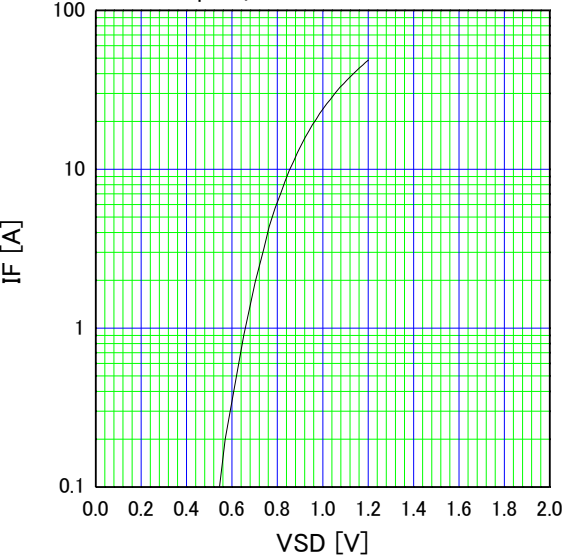
Typical Gate Charge Characteristics
 $V_{GS}=f(Q_g): I_D=22A, T_{ch}=25^\circ C$



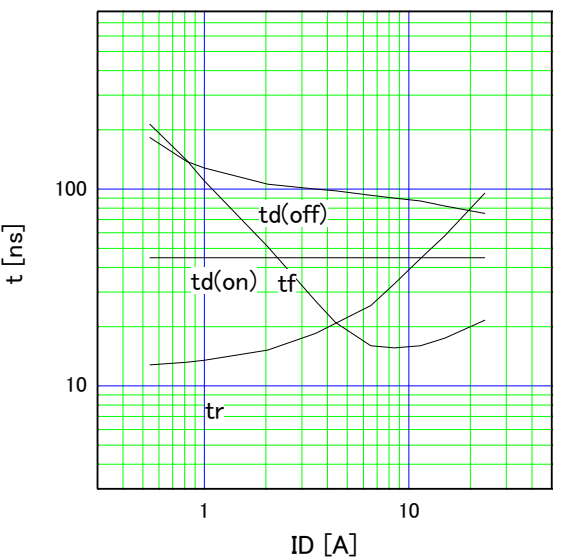
Typical capacitances
 $C=f(V_{DS}): V_{GS}=0V, f=1MHz$



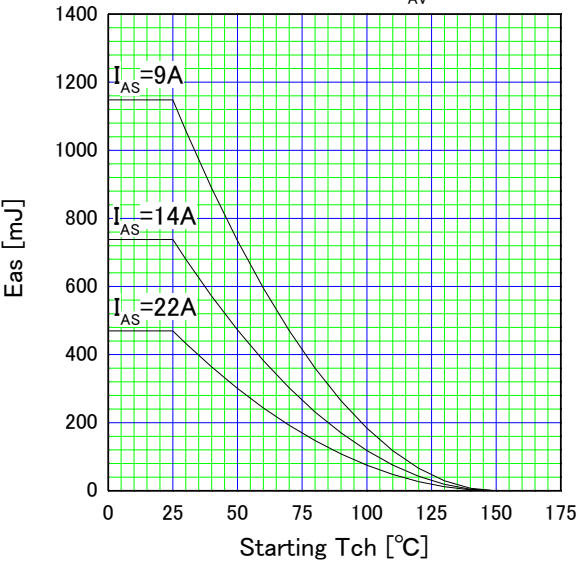
Typical Forward Characteristics of Reverse Diode
 $I_F=f(V_{SD}): 80\mu s \text{ pulse test}, T_{ch}=25^\circ C$



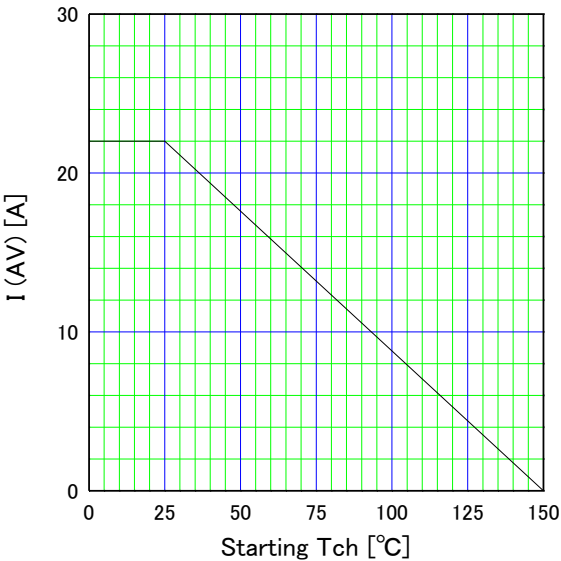
Typical Switching Characteristics vs. I_D
 $t=f(I_D): V_{cc}=300V, V_{GS}=10V, R_G=10\Omega$



Maximum Avalanche energy vs. starting T_{ch}
E_{as}=f (starting T_{ch}): V_{cc}=60V, I_{AS}≤22A, single pulse



Maximum Avalanche Current vs. starting T_{ch}
I (AV) =f (starting T_{ch}), single pulse



Maximum Transist Thermal Impedance
Z_{th(ch-c)}=f (t): D=0

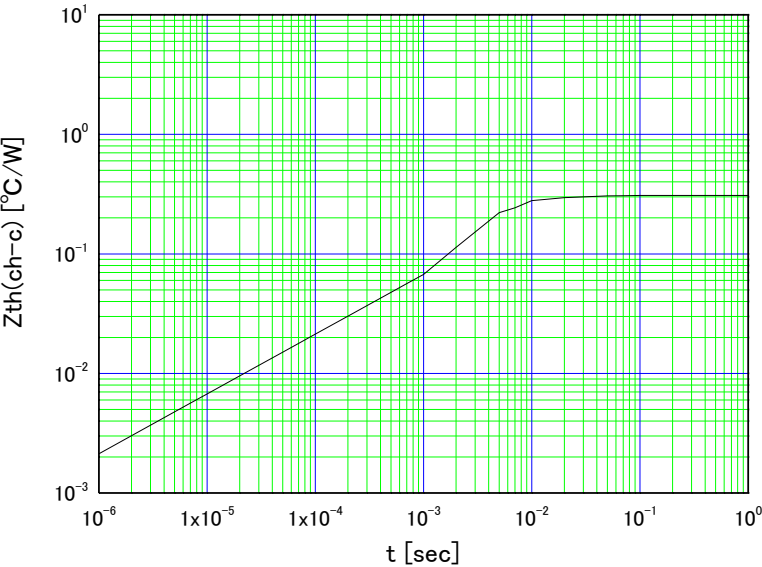


Fig.1 Avalanche Test circuit

Fig.2 Operating waveforms of Avalanche Test

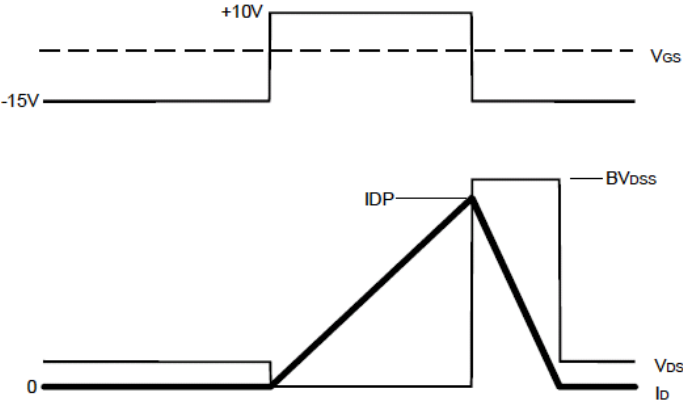
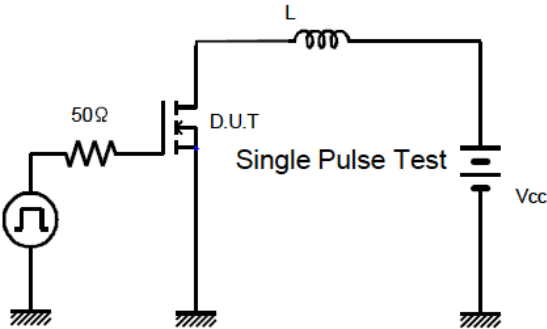


Fig.3 Switching Test circuit

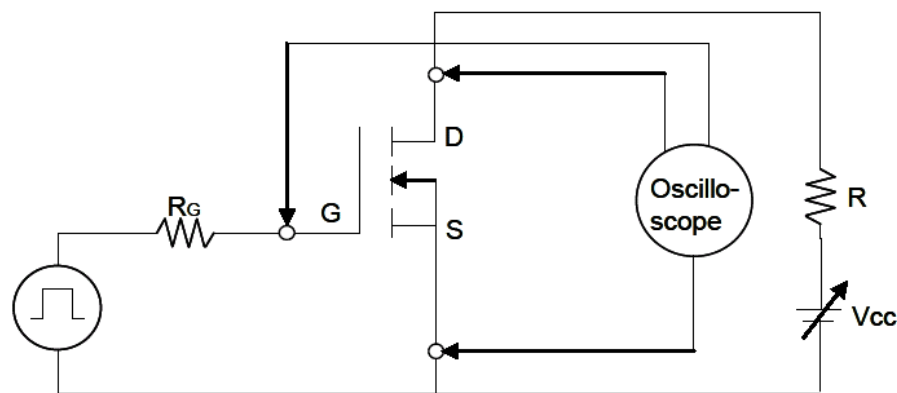


Fig.4 Operating waveform of Switching Test

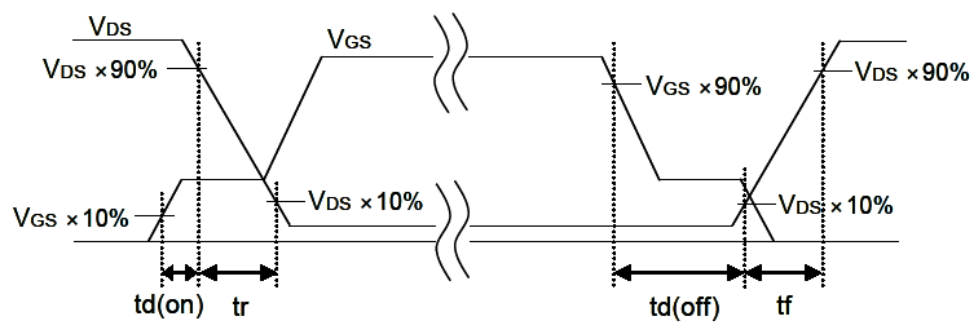


Fig.5 Operating waveform of Gate charge Test

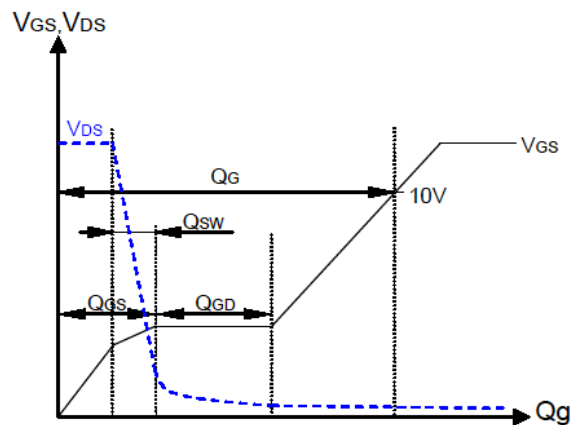
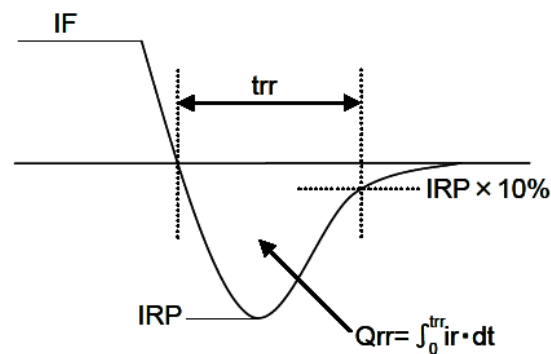


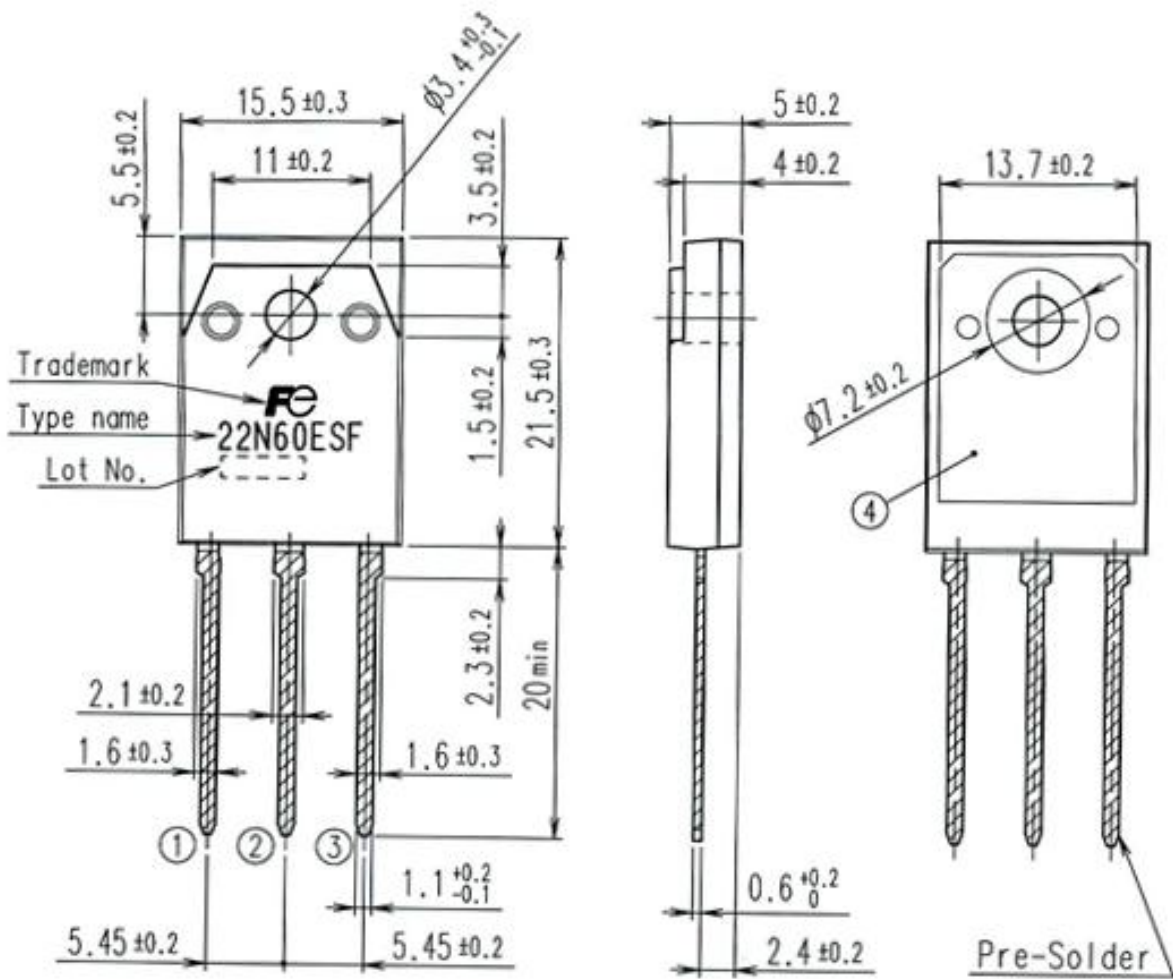
Fig.6 Operating waveform of Body diode Recovery Test



■ Out view

FUJI POWER MOSFET

TYPE : FMY22N60ESF



CONNECTION

- ① GATE
- ② ④ DRAIN
- ③ SOURCE

JEDEC: TO-247

DIMENSIONS ARE IN MILLIMETERS.

WARNING

1.This Data Sheet contains the product specifications, characteristics, data, materials, and structures as of Jun 2013.

The contents are subject to change without notice changes or other reasons.

When using a product listed in this Data Sheet, be sure to obtain the latest specifications.

2.All applications described in this Data Sheet exemplify the use of Fuji's products for reference only.

No right or license, either express or implied, under any patent, trade secret or other intellectual property right owned by Fuji Electric Co., Ltd. is (or shall be deemed) granted.

Fuji Electric Co., Ltd. makes no representation or warranty, whether express or implied, relating to the infringement or alleged infringement of other's intellectual property rights which may arise from the use of the applications described herein.

3.Although Fuji Electric Co., Ltd. is enhancing product quality and reliability, a small percentage of semiconductor products may become faulty.

When using Fuji Electric semiconductor products in your equipment, you are requested to take adequate safety measures to prevent design failsafe, flame retardant, and free of malfunction.

4.The produced introduced in this Data Sheet are intended for use in the following electronic and electrical equipment which has normal reliability requirements.

- Automotive · Computers · OA equipment · Communications equipment (Terminal devices)
- Machine tools · AV equipment · Measurement equipment · Personal equipment · Industrial robots
- Electrical home appliances etc.

5.If you need to use a product in this Data Sheet for enquiring higher reliability than normal, such as for the equipment listed below, it is imperative to contact Fuji Electric Co., Ltd. to obtain prior approval.

When using these products for such equipment, take adequate measures such as a backup system to prevent the equipment from malfunctioning even if a Fuji's product incorporated in equipment becomes faulty.

- Backbone network equipment · Transportation equipment (automobiles, trains, ships, etc.)
- Traffic-signal control equipment · Gas alarms, leakage gas auto breakers
- Medical equipment · Burglar alarms, fire alarms, emergency equipment etc.

6.Do not use products in this Data Sheet for the equipment requiring strict reliability such as the following and equivalents strategic equipment (without limitation).

- Aerospace equipment · Aeronautical equipment
- Nuclear control equipment · Submarine repeater equipment

7. As for a part of this Data Sheet or all the reprint reproductions, the approval of Fuji Electric Co., Ltd. by the document is necessary.

8.If you have any question about any portion in this Data Sheet , ask Fuji Electric Co., Ltd. or its sales agents before using the product.

Neither Fuji Electric Co., Ltd. nor its agents shall be liable for any injury caused by any use of the products not in accordance with instructions set forth herein.